Special Issue

New Technologies in Intelligent Manufacturing and Industrial Engineering, 2nd Edition

Message from the Guest Editors

Intelligent manufacturing and industrial engineering are undergoing rapid transformation with the emergence of new technologies. This Special Issue explores recent advancements and applications in this area, focusing on integrating cutting-edge technologies to enhance efficiency, productivity, and sustainability. We invite high-quality scientific papers that present original research and reviews on various aspects of intelligent manufacturing and industrial engineering. We welcome submissions focusing on, but not limited to, the following topics:

- Artificial intelligence and machine learning applications in manufacturing.
- Robotics and automation in industrial processes.
- Additive manufacturing (3D printing) technologies and applications.
- Cyber-physical systems and smart manufacturing.
- Internet of Things (IoT) for industrial applications.
- Advanced materials and nanotechnology in manufacturing.
- Sustainable manufacturing practices and green technologies.
- Digital twins and virtual manufacturing environments.
- Human factors and ergonomics in industrial engineering.
- Supply chain optimization and logistics management.
- Quality control and Six Sigma methodologies.

Guest Editors

Dr. Daniel Jancarczyk

Dr. Marcin Bernaś

Prof. Dr. Tomasz Boczar

Deadline for manuscript submissions

30 November 2025

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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